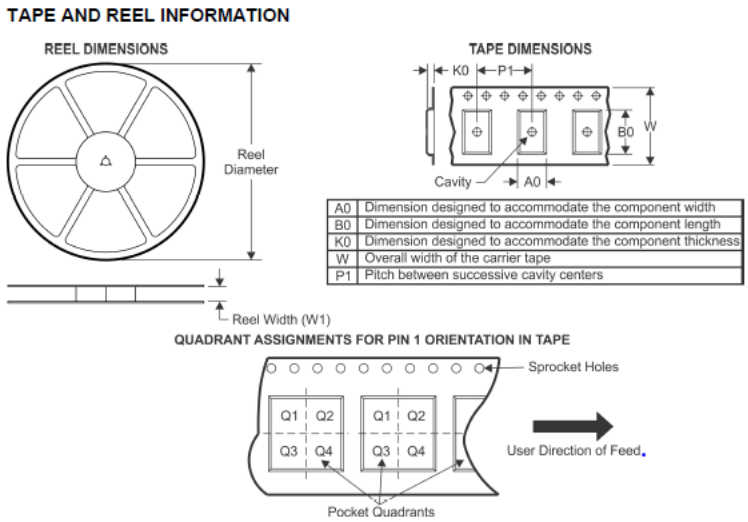
物料编码 Part number	供应商名称 Supplier Name	物料信息 Info of material				最小包装信息 Info of inner packing					
		包装方式 Packing type	料带宽度 Width of tape (MM)	开孔方式 Feeding hole type	物料步距 Feeding step （MM）	内装数量 Qty	毛重 Gross weight (KG)	包装件长 Length (MM)	包装件宽 Width (MM)	包装件高 Hight (MM)	包装材质 Material
TPD6S300	TI	tape reel	12.4		8	3000		367	367	35	PIZZA BOX



Marking picture	vendor Name （供应商名称）	Part No. （器件型号）	Marking Rule (丝印规则)
See datasheet	TI	TPD6S300	丝印 6S30A 代表型号，通过识别本体丝印 6S30A 可判定物料正确 the marking "6S30A" represents the device name, by identifying units marking 6S30A correctly to determine device

TI Part	*拆分部位名称 Disassembly Unit/component description	*均质材料名称 Homogeneous Material Name.	物质名称 Substance Name	*CAS No.	*物质重量 Substance Mass. (mg)	Content Rate(%)（均质材料中的含量
TPD6S300	Bond Wire	Copper and Its Alloys	Copper	7440-50-8	0.158062	99.997469
		Copper and Its Alloys	Iron	7439-89-6	0.000001	0.000633
		Other Inorganic Materials	Sulfur	7704-34-9	0.000001	0.000633
		Precious Metals	Silver	7440-22-4	0.000002	0.001265
	Die Attach Adhesive	Precious Metals	Silver	7440-22-4	0.460227	79.999965
		Thermoplastics	Epoxy	85954-11-6	0.115057	20.000035
	Lead Frame	Copper and Its Alloys	Copper	7440-50-8	15.6032	97.52
		Copper and Its Alloys	Iron	7439-89-6	0.368	2.3
		Copper and Its Alloys	Phosphorus	7723-14-0	0.0048	0.03
		Zinc and Its Alloys	Zinc	7440-66-6	0.024	0.15
	Lead Frame Plating	Nickel and Its Alloys	Nickel	7440-02-0	0.4756	95.12
		Precious Metals	Gold	7440-57-5	0.0039	0.78
		Precious Metals	Palladium	7440-05-3	0.0205	4.1
	Mold Compound	Other Inorganic Materials	Fused Silica	60676-86-0	7.449482	87.999994
		Other Organic Materials	Chlorine	7782-50-5	0.000085	0.001004
		Other Plastics and Rubber	Carbon Black	1333-86-4	0.025396	0.3
		Thermoplastics	Epoxy	85954-11-6	0.990358	11.699001
	Semiconductor Device	Ceramics / Glass	Doped Silicon	7440-21-3	1.272843	100

类别 Category	Basic Information		Result
	器件型号 Device Part Number		TPD6S300
晶圆信息 Wafer related Information	晶圆代工厂信息，工艺类别和工艺节点 Wafer fab information, process type and node		TI Confidential
	该晶圆工艺已经使用多长时间 Number of year/months since this wafer process was qualified and released to production.		TI Confidential
	有多少个产品已经使用了该晶圆工艺 How many of your products have been applied with this wafer process?		TI Confidential
	客户已使用的同晶圆族器件（同工艺技术、同工厂） Is there any part from the same wafer process family have been used in customer? If yes, please list the part number.		TI Confidential
封装信息 Assembly related Information	封装代工厂，封装类型 Assembly Factory, Package type		See TI.com
	封装尺寸（长*宽*高） Package Size (Length*Width*Height)		3x3x0.75mm, see latest datasheet
	焊球/引脚间距 Ball/Lead pitch		0.4MM, see latest datasheet
	客户已使用的同封装族器件（同封装技术、同封装厂） Is there any part from the same package family have been used in customer? If yes, please list the part number.		TI Confidential
	键合工艺 Wire Bonding (Only for Wire Bonding Package)	键合线成分 Wire composition	TI Confidential
		键合线直径 Wire diameter	TI Confidential
器件基本规格 General Specification	工作温度范围 Range of Operation Temperature （Ta, Tj or Tc）		-40~85C, see latest datasheet
	存储温度范围 Storage Temperature range		-65 ~ 150C, see latest datasheet
	存储期限 Storage limit		2years
	最大结温 Max.Junctioin Temperature		NA, see latest datasheet

	长期失效率 IFR, Intrinsic Failure Rate, FIT		0.1FIT@60%CL, see ti.com
	潮湿敏感等级 MSL, Moisture Sensitive Level		MSL 2, see latest datasheet
	封装热阻 Theta ja, jc and jb	Θja	45.2 °C/W, see latest datasheet
		Θjc	48.8 °C/W, see latest datasheet
		Θjb	17.1 °C/W, see latest datasheet
	ESD (HBM、CDM, for all pin)	HBM	2000, see latest datasheet
		CDM	500, see latest datasheet
	抗闩锁能力 Latch-Up (At max. Ambient Temperature)		TI follows the guidelines set forth by JEDEC standards as listed in the device datasheet

Check Items			**Result**
引脚/端子材料 Materials of Lead / termination	表面镀层 Surface plating/ coating material	材料成分 Composition	***NiPdAu***
		厚度(μm) Thickness(μm)	***TI Confidential***
	引脚基体材料 Basic metal		***TI Confidential***
元器件封装 Package	封装遵循的标准 Package standard		***JEDEC***
	元器件重量 Weight of component (g)		***0.027***
	元件重量/贴片吸取面积是否≤0.06g/mm2 Weight/ available P&P area ≤0.06g/mm2		***是 Yes***
			如果不满足，请给出具体值: ***If not，give the actual data:***

	共面度 coplanarity	整个回流过程中共面度（三个引脚、焊端及其以上适用/mm） coplanarity during reflow process	***refer to datasheet***
	1 脚标识 Mark point	器件上表面 MARK 信息是否有方向性标志点（例如“1”引脚标志）？ Is there any Mark point in the top side of component?	***是 Yes, subject to any variances in the datasheet***
		器件表面方向性标志点是否唯一?(如果不唯一请附图说明标志点与引脚对应关系。) Is the mark point sole? (if not, pls. give the relationship between mark and terminals)	***是 Yes, subject to any variances in the datasheet***
		器件资料是否明确标注引脚位置号？ Is there any specific location number of terminals in the component specification?	***是 Yes, subject to any variances in the datasheet***

		方向性器件在AOI 上实际确认，需要设备能识别器件极性 component orientation can be Identified by mounting machine or AOI?	***是 Yes, subject to any variances in the datasheet***
	密封性 seal	器件底部/焊端附近是否存在助焊剂渗入导致器件功能不良的孔或缝隙？ Is there any hole or gap in package body, flux enter pacakage inside form the hole or gap, resulting in function fail	***无孔或缝隙，密实性好 Yes, subject to any variances in the datasheet***
	器件本体的裸露非绝缘体（非焊接位置的金属/半导体等） exposed Non-insulator on component body	非焊接位置，是否存在裸露非绝缘体？裸露非绝缘体与邻近焊接引脚是否为同一网络属性？ Whether there exist non-insulator at no soldering position. Are non-insulator and adjacent soldering pin the same circuit?	***NO***

		所有裸露非绝缘体的尺寸和位置在器件规格书中是否图示标注清楚？ Have Dimension and Position of non-insulator been indicated in component spec.	***是 Yes, subject to any variances in the datasheet***
器件环保要求 requirements of environment compliant	下面所列物质的重量比是否满足 RoHS 要求？（请参考此调查表的“sheet7 RoHS Compliant”） 铅、镉、汞、六价铬、多溴联苯、多溴二苯醚 Are matters RoHS compliant listed below? (please refer to "sheet7 RoHS Compliant" in this file) Lead, Cd, Hg, Cr VI, PBB, PBDE Lead-free		***是 Yes, subject to any variances in the datasheet***
	是否无卤 Halogen-free		***是 Yes, subject to any variances in the datasheet***
元器件存储、包装、湿敏等级 Storage, packing MSD	相对湿度（%） Relative humidity (%)		***Per Jedec***
			其它 other (please specify):
	温度（℃） Temperature (℃)		***Per Jedec***
			其它 other (please specify):
	可存储期限（月） Maximum storage time (month)		***Follow MSL Guidelines***
	表贴元器件包装类型 Packaging type		***卷带包装 tape and real***
			其它 other(please specify):
	器件 pin1 脚标识在包装中的位置（见右图 2） Position of component pin 1 in packing（see right figure 2）		***figure②***

	料带或 Tray 盘高度（H），见右图 3 Packaging height(H),see right figure 3	***1.1 mm, subject to any variances in the datasheet***
	包装宽度（W）,见右图 3 Packaging width(W),see right figure 3	***12.4mm, subject to any variances in the datasheet***
	卷带器件料带步距:P1 component pitch:P1	***8mm, subject to any variances in the datasheet***
	防静电包装 ESD packaging	***是 Per JEDEC Guidelines***
	能否满足：料带包装中侧翻率≤0.05% Rollover rate ≤0.05% in packing	***是 TI follows the guidelines set forth by JEDEC standards as listed in the device datasheet***
	能否满足：卷带包装，器件在料槽旋转角度是否小于 10° Maximum component rotation for punched ≤10°	***是 TI follows the guidelines set forth by JEDEC standards as listed in the device datasheet***
	能否承受：托盘包装 125℃/24 小时的烘烤条件 tray packing Baking conditions: 125℃@24h	***是 TI follows the guidelines set forth by JEDEC standards as listed in the device datasheet***
	能否承受：卷带包装 40℃/192 小时的烘烤条件 reel tape packing Baking conditions: 40℃@192h	***是 TI follows the guidelines set forth by JEDEC standards as listed in the device datasheet***
	卷带包装是否符合 EIA 481 标准? can reel tape packing meet EIA 481 standard?	***TI follows the guidelines set forth by JEDEC standards as listed in the device datasheet***
	潮湿敏感等级 MSL	***2, subject to any variances in the datasheet***
	受潮后的烘烤要求是否满足 J-STD-033？ Baking requirement if	***是 TI follows the guidelines set forth by JEDEC standards as listed in the device datasheet***

	moisture meets J-STD-033？	
	潮敏等级在 2 级及 2 级以上，潮敏防护必须包含：潮敏指示卡、干燥剂、潮敏等级标识等 Moisture sensitive level at level 2 and level 2 above, moisture sensitive protection must include: moisture sensitive indicator card, desiccant, moisture sensitive grade logo	***是 TI follows the guidelines set forth by JEDEC standards as listed in the device datasheet***
组装工艺 Assembly process	能否满足：烙铁空载实测温度 400℃，每个引脚焊接时间≥5 秒。或者热风枪加热，器件本体温度达到 340℃以上时间 ≥10S。按照上述方法实现焊接后，器件外观要无损伤，电气性能要满足要求 manual soldering conditions：soldering iron tip temperature 400℃，time≥5s。 Or hot gun temperature340℃，time≥10s	***是 TI follows the guidelines set forth by JEDEC standards as listed in the device datasheet***
	是否满足：能承受的回流焊接次数≥3 次 Maximum soldering times ≥3	***是 TI follows the guidelines set forth by JEDEC standards as listed in the device datasheet***
	针对表贴器件，其耐温性是否满足 J-STD-020D 要求？（重点关注耐温性和回流曲线分级两部分，即表 4-1，4-2 和 5-2，请参考此调查表“sheet6 J-STD-020D”） Can heat resistance of SMT components meet JSTD020D. (should focus on the classification of temperature and reflow profiles, that is table 4-1, 4-2 and 5-2, please refer to	***是 TI follows the guidelines set forth by JEDEC standards as listed in the device datasheet***

	sheet6 J-STD-020D in this file)	
	是否满足：表贴器件中心能承受的贴片压力≥2N Maximum pick-and-place pressure (N)	***是 TI follows the guidelines set forth by JEDEC standards as listed in the device datasheet***
	器件的焊接加工和设计要求是否已经全部写入器件规格书？ Whether the welding process and design requirements of component have all written to the component specifications	***是 TI follows the guidelines set forth by JEDEC standards as listed in the device datasheet***
	器件规格书中提供的焊盘及钢网设计（包括钢网厚度）是否为强制要求？ Whether Pad & stencil design as Mandatory requirements in component spec?	***推荐 recommended***
	器件对回流焊升温斜率和降温斜率是否有特殊要求？客户采用 J-STD-002D 标准 Whether the device has special requirements for the reflow temperature ramp-up rata and ramp-down rata? Customer follow J-STD-002 standard	***无 TI follows the guidelines set forth by JEDEC standards as listed in the device datasheet***
	器件规格书中有无其他强制要求？ Are there other mandatory requirements in component spec?	***无 Please refer to datasheet.***
测试报告 Test Report	可焊性测试报告 Solderability test report	***See ti.com for qual report.***
	工艺板级可靠性测试报告 Board level reliability test report	***See ti.com for qual report.***

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